CLAIMS

1. A bonding apparatus comprised of a processing member that processes bonding parts, a first imaging device that images a specific pattern, and a first offset calculating means that calculates an amount of offset between said processing member and said first imaging device based upon image data acquired by said first imaging device, said bonding apparatus further comprising:

a second imaging device that images said specific pattern, and

a second offset calculating means that calculates an amount of deviation between a reference point of a first image data acquired by said first imaging device and a reference point of a second image data acquired by said second imaging device based upon said first image data and said second image data.

2. The bonding apparatus according to Claim 1, wherein said second offset calculating means calculates said amount of deviation between said reference point of said first image data and said reference point of said second image data based upon:

a first magnification which is an imaging magnification of said first imaging device, and

a second magnification which is an imaging magnification of said second imaging device.

3. The bonding apparatus according to Claim 2, wherein said second offset calculating means:

performs reduction processing so that the image data with a higher magnification among image data obtained by said first imaging device and image data obtained by said second imaging device are caused to match an imaging magnification on a lower magnification side, and

compares an image obtained by said reduction processing with said image data on said lower magnification side.

4. A bonding method used in a bonding apparatus which is comprised of a processing member that processes bonding parts, a first imaging device that images a specific pattern, a second imaging device that images said specific pattern, and a first offset calculating means that calculates an amount of offset between said processing member and said first imaging device based upon image data acquired by said first imaging device, wherein:

said method calculates an amount of deviation between a reference point of a first image data acquired by said first imaging device and a reference point of a second image data acquired by said second imaging device, said calculation being performed based upon said first image data and said second image data.

5. The bonding method according to Claim 4, wherein said amount of deviation between said reference point of said first image data and said reference point of said second image data is calculated based upon a first magnification which is an imaging magnification of said first imaging device and a second magnification which is an imaging magnification of said second imaging device.

6. The bonding method according to Claim 5, wherein said method includes:

a step of performing a reduction processing so that image data with a higher magnification among image data obtained by said first imaging device and image data obtained by said second imaging device is caused so as to match imaging magnification on a lower magnification side, and

a step of comparing data subjected to said reduction processing with said image data on said lower magnification side.